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Abstract of the Disclosure:

On a substrate, first and second electrical connecting elements of an integrated circuit are disposed next to one another along a first direction. The first electrical
5 connecting element is at a first distance from the second electrical connecting element. First and interconnects are disposed on the substrate, the first interconnect being connected to the first electrical connecting element and the second interconnect being connected to the second electrical
10 connecting element. Third and fourth electrical connecting elements are disposed on the substrate and the first and second interconnects are disposed between the third and fourth electrical connecting elements and therebetween are at a second distance from one another, the second distance being
15 smaller than the first distance.

GLM/nt